ASSOCIATION CONNECTING	Material Composit © Copyright 2005. IPC, international and Pan-Art	t ion Dec Bannockb nerican co	claration urn, Illinois. A pyright conver	ll rights reserved untions.	under both	This docume level parts, t	ent is a declar he declaration	ration of n encon	f the substances npasses all lowe	within t r level n	he manufactu naterials for v	rer listed it which the m	em. Note anufactu	e: if the item arer has engi	is an asse neering re	mbly with low sponsibility.
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information										
Supplier Informa	ation															
Company name* Company ur				que ID			Unique ID Authority				Respons	Response Date*				
nsemi												2025-05-	12			
ontact Name			Title - Contact				Phone - Contact*				Email -	Email - Contact*				
Product-Env-Stewar	ds		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*						
Product-Env-Stewards			Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Requester			Number Mfr Item Name				Effective Da	ate Ve	ersion 1	Manufacturing Site		V	Weight*	UOI	М	Unit Type
			XGS5MP, 16port, Color		2025-05-12			TA1		1	189.09	mg		Each		
Ianufacturing P	Proccess Information	1												1		•
Terminal Plating / Grid Array Material Te		erminal Base A	Alloy	J-STD-020 MSL R		Peak Process		Body Temperature Max Tim		Time at Peak	ak Temperature N		Number of Reflow Cycles			
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy		4		245 C		30 seco		second	seconds 3					
omments																
or more information	n regarding material com	position	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.												
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	220.55	mg		Misc.	proprietary data		0.8381	mg
			Supplier	Silicon (Si)	7440-21-3		217.5285	mg
			Supplier	Aluminum (Al)	7429-90-5		2.1834	mg
Die Attach Epoxy	45.39	mg	Supplier	2,2-bis(acryloyloxymethyl)butyl acrylate	15625-89-5		34.0425	mg
			Supplier	Imidazole Addition	68490-66-4		1.3617	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		6.8085	mg
			Supplier	Silica (SiO2)	14464-46-1		3.1773	mg
naging Lens	456.52	mg	Supplier	Sulfur (S)	7704-34-9		2.2826	mg
			Supplier	Titanium Dioxide (TiO2)	13463-67-7		22.826	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		22.826	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		22.826	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		22.826	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		22.826	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		22.826	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		317.2814	mg
Lid Attach	5.77	mg		Epoxy resin	proprietary data		4.6679	mg
			Supplier	Adeka Optomer SP 150	125054-47-9		0.1385	mg
			Supplier	Photoinitiator	Proprietary Data		0.427	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.5366	mg
Mold Compound-Black	256.37	mg		Phenolic Resin	proprietary data		38.4555	mg
			Supplier	Oxirane	39817-09-9		38.4555	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		7.6911	mg
			Supplier	Carbon Black (C)	1333-86-4		2.5637	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		164.0768	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		5.1274	mg
Substrate	202.55	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		42.9406	mg
			Supplier	Inorganic filler	Proprietary Data		26.4935	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		2.6534	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.6482	mg
			Supplier	Acetophenone Derivative	Proprietary Data		3.97	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6684	mg

			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.6684	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	7.94	mg
			Supplier	Copper (Cu)	7440-50-8	96.0492	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	20.5183	mg
Wire Bond - Au	1.94	mg	Supplier	Gold (Au)	7440-57-5	1.94	mg